

# SID

Factory: Rot am See

Article:

570

ML8

Provided:

Landwehr, Melanie

Customer:

Date:

17.12.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	123		2	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		3	
A-RS-FR4-ML-0.51mm-035+035-TG150-HF	50200644	35	L2		A01
		510		4	
		35	L3		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	105		5	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		6	
A-RS-FR4-ML-0.51mm-035+035-TG150-HF	50200644	35	L4		A02
		510		7	
		35	L5		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	105		8	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		9	
A-RS-FR4-ML-0.51mm-035+035-TG150-HF	50200644	35	L6		A03
		510		10	
		35	L7		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	123		11	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		12	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	13	

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

2266 µm

Version 1.2.14.15

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